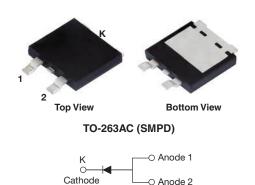
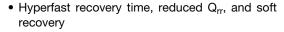


Hyperfast Rectifier, 16 A FRED Pt®



PRODUCT SUMMARY				
Package	TO-263AC (SMPD)			
I _{F(AV)}	16 A			
V_{R}	200 V			
V _F at I _F	0.75 V			
t _{rr}	32 ns			
T _J max.	175 °C			
Diode variation	Single die			

FEATURES





RoHS

COMPLIANT **HALOGEN**

FREE

- 175 °C maximum operating junction temperature
- Specified for output and snubber operation
- Low forward voltage drop
- Low leakage current

• Meets MSL level 1, per J-STD-020, LF maximum

- peak of 260 °C AEC-Q101 qualified, meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers specifically designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness, and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, telecom, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce power dissipation in the switching element.

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Peak repetitive reverse voltage	V_{RRM}		200	V		
Average rectified forward current	I _{F(AV)}	T _{solder pad} = 152 °C	16	۸		
Non-repetitive peak surge current	I _{FSM}	T _J = 25 °C, 6 ms square pulse	250	А		

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	MBOL TEST CONDITIONS MIN. TYP. MAX.		MAX.	UNITS	
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	200	-	-	
Forward voltage V _F	W	I _F = 16 A	=	0.91	1.0	V
	I _F = 16 A, T _J = 150 °C	=	0.75	0.84		
Devenue le clarac comment		V _R = V _R rated	-	-	15	
Reverse leakage current	I _R	T _J = 150 °C, V _R = V _R rated	=	20	500	μΑ
Junction capacitance	C _T	V _R = 200 V	-	60	-	pF



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
		$I_F = 1 A, dI_F/dt = 50 A$	$I_F = 1 \text{ A}, dI_F/dt = 50 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		32	1	
Reverse recovery time t _{rr}		I _F = 0.5 A, I _R = 1 A, I _{rr} = 0.25 A		-	-	32	
	L _{rr}	T _J = 25 °C		-	26	-	ns
		T _J = 125 °C		-	40	-	
Peak recovery current I _{RRM}	1	T _J = 25 °C	$I_F = 16 \text{ A},$ $dI_F/dt = 200 \text{ A/}\mu\text{s},$ $V_R = 160 \text{ V}$	-	2.8	-	Α
	IRRM	T _J = 125 °C		-	6	-	
Reverse recovery charge C	0	T _J = 25 °C		-	37	-	nC
	Q _{rr}	T _J = 125 °C		-	125	-	110

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	+175	°C
Thermal resistance, junction to solder pad	R _{thJ-Sp}		-	1.1	1.5	°C/W
Approximate weight				0.55		g
Approximate weight				0.02		oz.
Marking device		Case style TO-263AC (SMPD)		16EI	DH02	

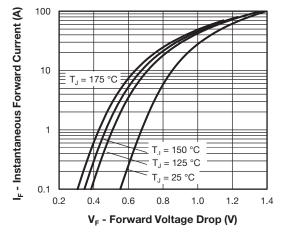


Fig. 1 - Typical Forward Voltage Drop Characteristics

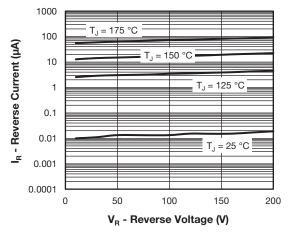


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

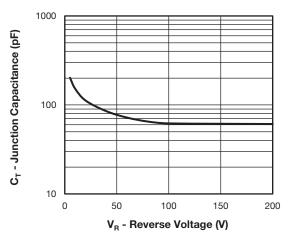


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

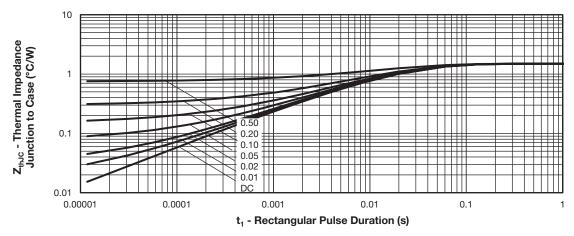


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

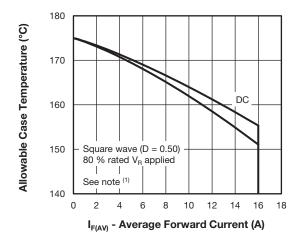


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

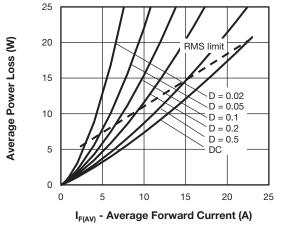


Fig. 6 - Forward Power Loss Characteristics

Note

⁽¹⁾ Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$; $Pd = Forward power loss = I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 5); $Pd_{REV} = Inverse power loss = V_{R1} \times I_R$ (1 - D); I_R at $V_{R1} = rated V_R$

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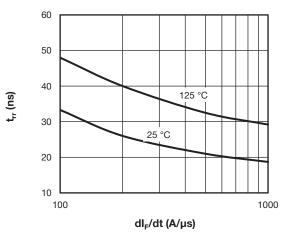


Fig. 7 - Typical Reverse Recovery Time vs. dI_F/dt

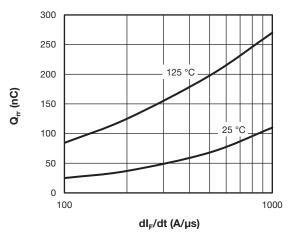
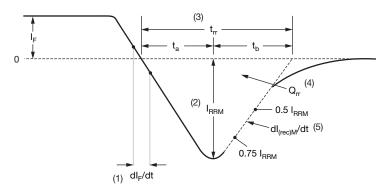


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

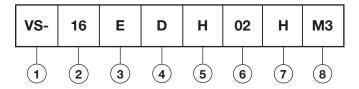
(5) dl_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (16 A)

3 - Circuit configuration:

E = single die

4 - D = SMPD package

5 - Process type,

H = hyperfast recovery

6 - Voltage code (02 = 200 V)

7 - H = AEC-Q101 qualified

8 - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)						
PREFERRED P/N	QUANTITY PER REEL	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-16EDH02HM3/I	2000	2000	13" diameter plastic tape and reel			

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95604			
Part marking information	www.vishay.com/doc?95566			
Packaging information	www.vishay.com/doc?88869			



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